Pain Points of Existing Elemental Analysis Techniques and a New Solution



EDX/EELS

- Long sample-prep times
- 3D analysis infeasible
- Low-Z elements challenging

Site-Specific SIMS

- Resolution limited to ~50 nm with high yield (CAMECA NanoSIMS), or
- Can get a high resolution FIB (Ga, He, Ne) with a time-of-flight SIMS analyzer. But low secondary ion yields from these beams usually results in poor lateral resolution. Additionally, time-of-flight analyzers necessitate **long** acquisition times.

These points are addressable by **SIMS:ZERO**

- Few-nanometer resolution (slide 4)
- High secondary ion yield (slides 6,7)
- Integrated sample-prep and analysis capability (slides 8-18)

07/2021

SIMS:ZERO

Instrument Overview

Cs+ FIB:ZERO (zeroK) and SIMS spectrometer (LIST: Luxembourg Institute of Science and Technology) on a 600 series FIB (FEI)

LoTIS Magnetic Focal LoTIS Ion [Plane Column Sector Detectors (4X) Primary Ion Spectrometer Beam Axis (Cs+) Electrostatic V SI Extraction Sector Optics Secondary Ion Beam Axis (+ or -) Sample FIB

- FIB online 6/2020
- SIMS online 5/2021

ZERØ

NANOTECH

FIB / SIMS Combination Sample Prep, Nanofabrication / Analysis, Process Control



FIB Mode







LoTIS capabilities

- 2-16 keV Cs+ beam
- Up to 5nA beam current
- Spotsize <2nm at low current
- Good spotsizes even at low beam energy

FIB Mode (SIMS Extraction Optics Retracted)

- Milling
- Sample Preparation (eg Sectioning, Polishing)
- Nanofabrication
- Gas-assisted processes (eg Platinum Deposition)
- Tilt stage

SIMS Mode (SIMS Extraction Optics Inserted)

- Highest spatial resolution SIMS imaging
 - $\sigma = 6 \text{ nm}$ demonstrated
- Mass resolution $M/\Delta M = 400$
- Mass range up to 300 amu
- High secondary ion throughput (~40% simulated)
- 4-Channel Detector Standard (Continuous Focal Plane Detector available)

SIMS:ZERO Resolution Tungsten Carbide



- SIMS:ZERO can provide higher resolution SIMS scans than any other instrument
- SIMS resolution is a function of abundance, yield, and spot size
- SIMS:ZERO has a focused ion beam with <3 nm spot size, and since it's Cs⁺ we achieve high yields for many materials
- In samples with high abundances, resolution at near the physical limits of SIMS can be achieved (see right)



Multi_WC_2105121624015_CH1.TIF



$\sigma = 6.1 nm$ (!)

Working Distance = 51.6mm 272s acquisition time.

Negative lons

Date	05/12/2021
Sample	WC (184 amu)
FOV (um)	2.97um
I (pA)	2.5
U (kV)	16

SIMS Analysis Example CIGS Cu(In,Ga)Se₂ – Rb doped



<u>Summary</u>

- CIGS is a solar cell absorber material
 - Rubidium doping increases conversion efficiency
- SIMS spectra clearly show all CIGS elements:
 - Cu, In, Ga, Rb in Positive Mode
 - Se, S in Negative Mode
- Secondary ion imaging channels show distribution of elements in sample, eg Rb dopants concentrated in grain boundaries
- Secondary electron images provide complementary information at high resolution
- Section view technique provides superior SIMS data





Werner, et al. <u>Scientific</u> <u>Reports</u> volume 10, 7530 (2020)

CIGS Cu(In,Ga)Se₂ – Rb doped Mass Spectra – Positive Ions



Start (mT) : 30.000000 Stop (mT) : 700.000000

Delta (mT): 0.100000

Period of beam acq:0

Pos CH1: 100.000675

Pos CH2 : 200.000362 Pos CH3 : 299.999717 Pos CH4 : 390.00000

Date

Sample

Aperture Slit

FOV (um)

I (pA)

U (kV)

Sampling rate (ms) : 250.000000 Waiting time (s) : 0.250000

06/23/2021

CIGS

100um

43

10

16



6

CIGS Cu(In,Ga)Se₂ – Rb doped Mass Spectra – Negative Ions





07/2021

06/24/2021

CIGS

100um

43

10

16

CIGS Cu(In,Ga)Se₂ – Rb doped Secondary Ion Image - Large FOV







Rb, In is everywhere on surface (window/buffer stack layer).

Signal variation largely due to topography

We have milled a crater to see subsurface structure, e.g. where Rb is confined to CIGS grain boundaries (see next slide).

Cs+, 16keV, 10pA 1ms dwell, 4.5min acquisition time CIGS_Pos_2107081255037.csv

CIGS Cu(In,Ga)Se₂ – Rb doped Secondary Ion Image - Smaller FOV - Crater





Rubidium dopants are found primarily along grain boundaries

Cs+ 16keV, 2.5pA, 51.6mm WD 1ms dwell, 4.5min acquisition time CIGS_Pos_2107081226114.csv



Indium signal determined primarily by topography not spatial distribution



Secondary electron image

(NOTE: somewhat deeper than where SIMS image was acquired)

CIGS Cu(In,Ga)Se₂ – Rb doped SE Images



Crater Geometry





Very rough, pointy surface topography develops while milling the crater

This kind of topography is reflected in the SIMS images, obscuring elemental contrast (Slide 9)

With proper sample sectioning techniques, we obtain more and better SIMS data (Slides 11-18)

Cs+, 16keV, 10pA, 51.6mm WD

SIMS-Compatible Section View 45° Angle Cut - Example





View with Sample Normal to Beam; Ready for SIMS on Section



For many samples, working with a section view is a sensible choice

- 1. Reveal sub-surface structure
- 2. Obtain depth profile data without accumulated topography from uneven sputtering
- Polish rough samples to isolate elemental from topographical contrast
- 4. Build 3D tomographic reconstructions through serial sectioning/polishing

In SIMS:ZERO, sample must be normal to ion beam in SIMS Mode, so section face is cut at 45° to sample surface

This sectioning is done in FIB mode. Switching between FIB and SIMS mode takes about 2 min

SIMS-Compatible Section View 45° Angle Cut – Sample Prep Example



Section Cut with Sample Tilted at 45°



View with Sample Tilted at 45° & Rotated 90°



View with Sample Normal to Beam; Ready for SIMS on Section

ZERØK Nanotech







CIGS Cu(In,Ga)Se₂ – Rb doped Serial Sectioning / Imaging / Polishing Work-Flow



SE Images



SIMS section, prepared with low surface topography, reveals layer structure (glass, moly, CIGS, Window/Buffer Stack)

After SIMS Imaging, section face develops topography which obscures elemental contrast / distribution information Section face after cleanup mill. Ready for SIMS on next layer

CIGS Cu(In,Ga)Se₂ – Rb doped Section View – Positive Ions



SE Image – Pre-SIMS



- Rb confined to grain boundaries
- Grains are smaller near the interfaces

Cs+, 16keV, 3.5pA, 51.6mm WD CIGS_Pos_2107161606287.csv CIGS_Pos_2107161613425.csv

CIGS Cu(In,Ga)Se₂ – Rb doped Section View – Positive Ions / Negative Ions / SE



Positive Mode



- Ga concentration gradient ↑
- Dark spots appear on image

Negative Mode



 Spherical drops containing Se develop on CIGS region after repeated imaging

SE Image – Post SIMS



 Unwanted topography can be cleaned up by polishing in FIB mode

> Cs+, 16keV, 3.5pA, 51.6mm WD CIGS_Pos_2107161613425.csv CIGS_Neg_2107161719423.csv

CIGS Cu(In,Ga)Se₂ – Rb doped Section View – Negative Ions – Post 2nd Polish





SE Image – Post Polish Low topography restored





Signal band in CIGS layer near moly may be sulfur, commonly used in CIGS fabrication process; inclusions near surface



Se is more uniformly distributed in CIGS layer; droplets at moly interface, a few inclusion near surface

> Cs+, 16keV, 10pA, 51.6mm WD CIGS_Neg_2107201513310.csv

CIGS Cu(In,Ga)Se₂ – Rb doped Section View – Positive Ions – Post 3rd Polish





Na – Soda Lime Glass

Ga concentration gradient ↑

In concentration gradient \downarrow

Cs+, 16keV, 10pA, 51.6mm WD CIGS_Pos_2107201626359.csv

CIGS Cu(In,Ga)Se₂ – Rb doped Section View – Positive Ions





Apparent width of Rubidium signal between grains



Cs+, 16keV, 3.5pA, 51.6mm WD CIGS_Pos_2107151409368.csv

Continuous Detector A SIMS: ZERO Option

- SIMS signals for a given element are split into many lines (e.g. Ti, TiO etc..).
- In discrete-detector systems this • leads to a loss of information and lower SNR.
- With continuous detector technology we can sample the entire mass spectrum at once.
- Now we can collect the entire • spectrum as in TOF systems, but without painfully long acquisition times.

(Top) Photo of SIMS spectrometer (at LIST) and the continuous focal plane detector mounted to a vacuum flange. (Bottom) A 480mm micro-channel plate that spans the focal plane of the spectrometer.

TiO₂ NPs on InP wafer

1000

100

sdo



surface compositional maps (Right). The sample under interrogation was titanium oxide nanoparticles on an indium phosphide substrate.





